



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Agarwala et al.

Docket No.: BUR920000215US1

Serial No.: 09/871,883

Group Art Unit: 2815

Filed: June 1, 2001

Examiner: Warren, Matthew E.

Title: DUAL-DAMASCENE MULTI-LEVEL METALLIZATION

#8/A
And
J. McNeill
10/28/02

Commissioner for Patents
Washington, D.C. 20231

This paper is being filed in response to the Office Action mailed on July 17, 2002.
Applicants request this Amendment be entered in the above-identified application and
reconsideration of the application in view of the Amendments and Remarks that follow.

AMENDMENT

Please amend the above-referenced patent application as follows:

In The Drawings

Please revise the drawings in accordance with the Request for Approval of Drawing
Corrections attached hereto.

In The Specification

Please cancel the present title and replace with "DUAL-DAMASCENE
METALLIZATION INTERCONNECTION"

In The Claims

Please amend claims 1, 10, 20 and 25 as indicated in Appendix A. Please cancel claims
5, 14, 21 and 26. Currently pending claims 1-4, 6-13, 15-20, 22-25, 27-35, are as follows:

1. (Once amended) An interconnect structure, comprising:

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